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By: 

Date: January 24, 2000

2826
#12/A

3-5-02
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FEB 23 2000
GENERAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hansjörg Reichert et al.
Applic. No. : 09/483,737
Filed : January 14, 2000
Title : Method and Apparatus for Producing a Chip-Substrate Connection
Examiner : Ahmed N. Sefer
Group Art Unit : 2826

A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Responsive to the Office action dated October 24, 2001 kindly
amend the above-identified application as follows:

In the Claims:

✓
Cancel claims 11-14 and 16.

~~Claim 15 (amended). A semiconductor component, comprising:~~

A1
Sub B1